

REMARKS

The Office Action of August 13, 2004 has been received and its contents carefully noted.

The present Amendment corrects a typographical error in the cross-reference to the parent of the present continuation application. The parent should have been identified as application number 10/057,909 (instead of 10/057,099). In addition to correcting this error in the serial number, the revision identifies the number of the patent that issued on the parent application.

The present Amendment also makes corrections in the claims. In the arrangement shown in Figures 1 and 2 of the present application's drawings, for example, it is the back side 105 of the semiconductor substrate (and not the resin 111) that has a section 107 (see the paragraph bridging pages 6 and 7 of the application). Accordingly, the present Amendment corrects the independent claims to conform to the disclosure, and makes revisions in the dependent claims where appropriate to conform them to the changes made in the independent claims. Dependent claims 78 and 79 have been cancelled.

The oversight in the claims that necessitated these corrections is regretted.

The Office Action allowed some of the claims but rejected others for anticipation by patent 4,970,575 to Soga et al. (this reference will hereafter be called simply "Soga"). For the reasons discussed below, it is respectfully submitted that the rejected claims are patentable over this reference. Moreover, in view of the corrections that had been made to the allowed claims, it is appropriate to consider whether they remain allowable over Soga.

As will be discussed in more detail below, it is respectfully submitted that they do indeed remain allowable.

First, it is appropriate to address claim 56, since this is the only independent claim that stands rejected in the Office Action. The Office Action comments generally that Soga's Figure 5A shows a stripe groove 21 formed on a second main surface of a molding resin structure 11, with the stripe groove 21 dividing the second main surface asymmetrically. However, claim 56 has been corrected to recite that a semiconductor chip has first and second chip surfaces, and that a stripe groove is "formed on the first chip surface, wherein the stripe groove divides the first chip surface asymmetrically." Soga's chips 1 lack such a stripe groove.

Independent claim 63 recites a steplike section that is "formed on one of the sides of the first chip surface." Independent claim 67 recites "a stripe portion formed on the first chip surface, ..., wherein the stripe portion divides the first chip surface asymmetrically." It is respectfully submitted that the "steplike section" of claim 63 and the "stripe portion" of claim 67 are neither disclosed nor suggested by Soga.

Since the remaining claims depend from the independent claims discussed above and recite additional limitations to further define the invention, they are patentable along with their independent claims and need not be further discussed.

For the foregoing reasons, it is respectfully submitted that this application is now in condition for allowance. Reconsideration of the application is therefore respectfully requested.

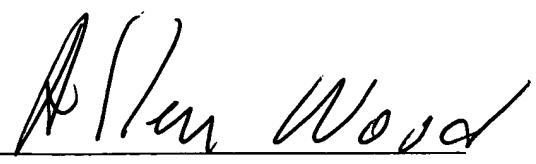
Respectfully submitted,

AMENDMENT

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